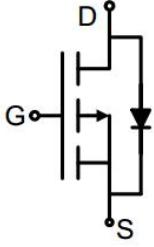
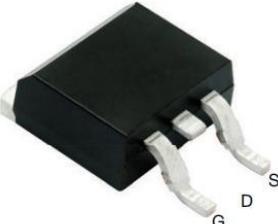


P-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The G900P15M uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} -150V ● I_D (at $V_{GS} = -10V$) -60A ● $R_{DS(ON)}$ (at $V_{GS} = -10V$) < 80mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>TO-263</p>
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Ordering Information			
Device	Package	Marking	Packaging
G900P15M	TO-263	G900P15	800pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-150	V
Continuous Drain Current	I_D	-60	A
Pulsed Drain Current (note1)	I_{DM}	-240	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	100	W
Single pulse avalanche energy (note2)	E_{AS}	132	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	°C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	50	°C/W
Maximum Junction-to-Case	R_{thJC}	1.25	°C/W

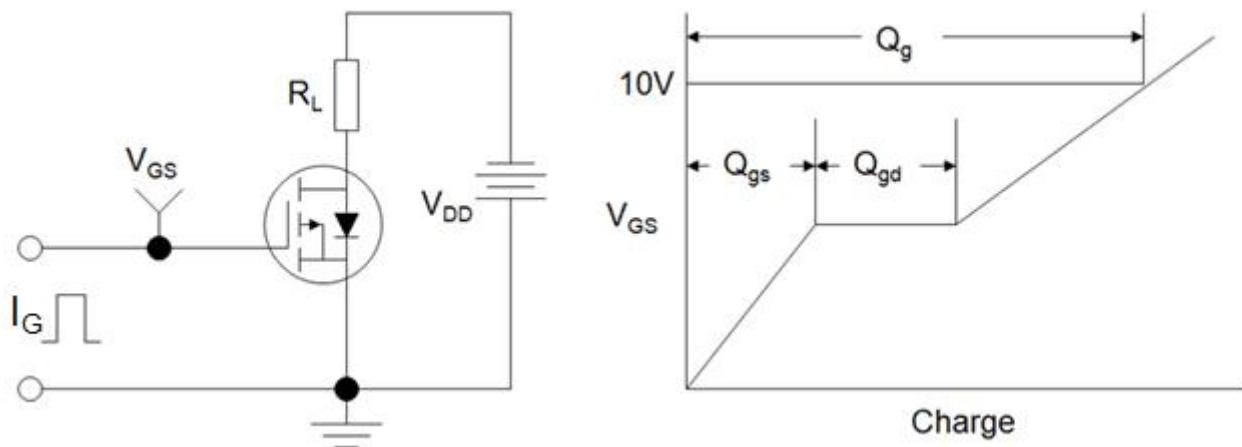
Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-150	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -150\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	-1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1	-2.6	-4	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -5\text{A}$	--	62	80	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -5\text{V}, I_D = -5\text{A}$	--	8	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -75\text{V}, f = 1.0\text{MHz}$	--	4056	--	pF
Output Capacitance	C_{oss}		--	148	--	
Reverse Transfer Capacitance	C_{rss}		--	109	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = -75\text{V}, I_D = -5\text{A}, V_{\text{GS}} = -10\text{V}$	--	27	--	nC
Gate-Source Charge	Q_{gs}		--	7	--	
Gate-Drain Charge	Q_{gd}		--	3	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -75\text{V}, I_D = -5\text{A}, R_G = 3\Omega$	--	10	--	ns
Turn-on Rise Time	t_r		--	9	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	29	--	
Turn-off Fall Time	t_f		--	4	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	-60	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = -5\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	-1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = -5\text{A}, V_{\text{GS}} = 0\text{V}$ $di/dt = -500\text{A}/\mu\text{s}$	--	434	--	nC
Reverse Recovery Time	T_{rr}		--	51	--	ns

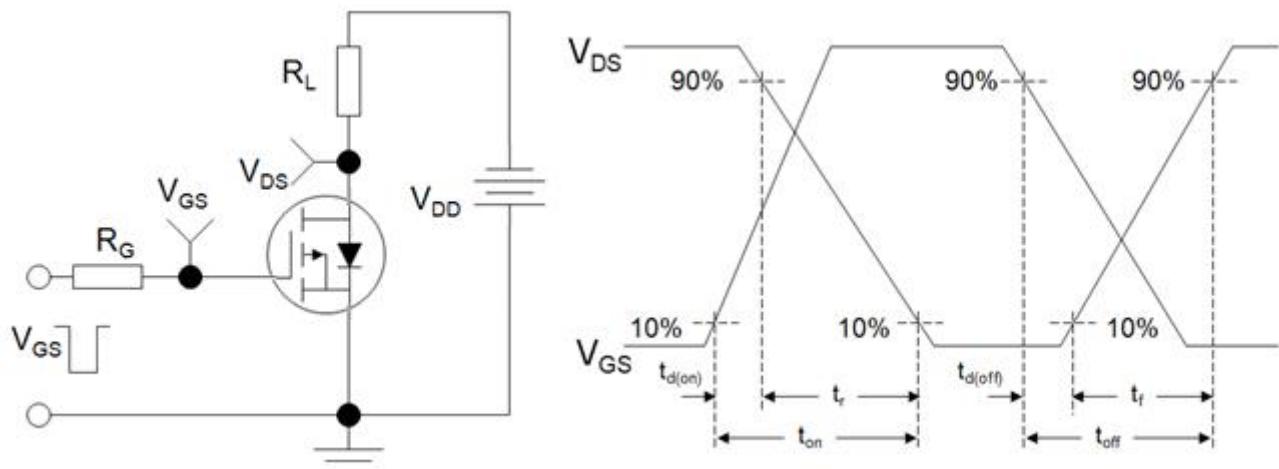
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
3. Identical low side and high side switch with identical R_G

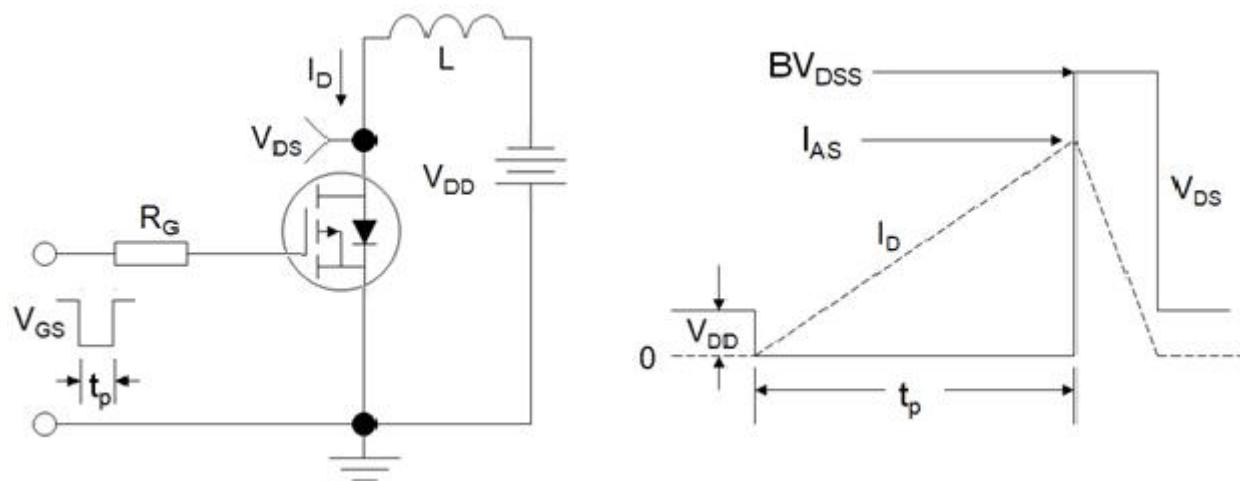
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

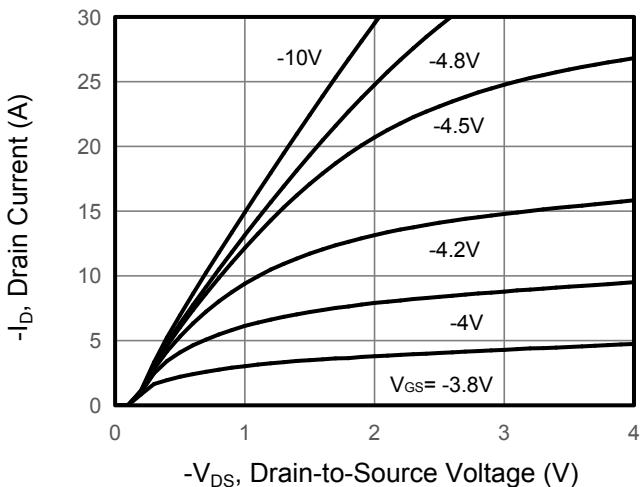


Figure 2. Transfer Characteristics

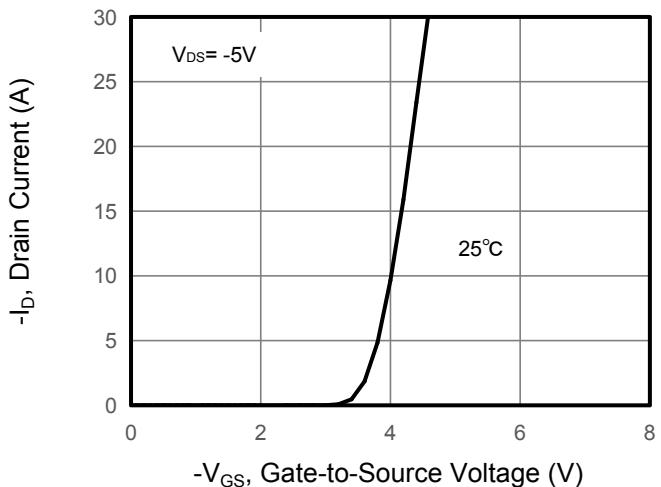


Figure 3. Drain Source On Resistance

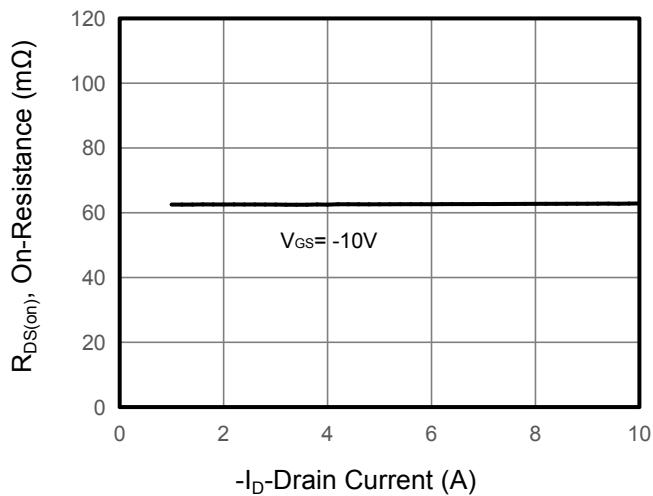


Figure 4. Gate Charge

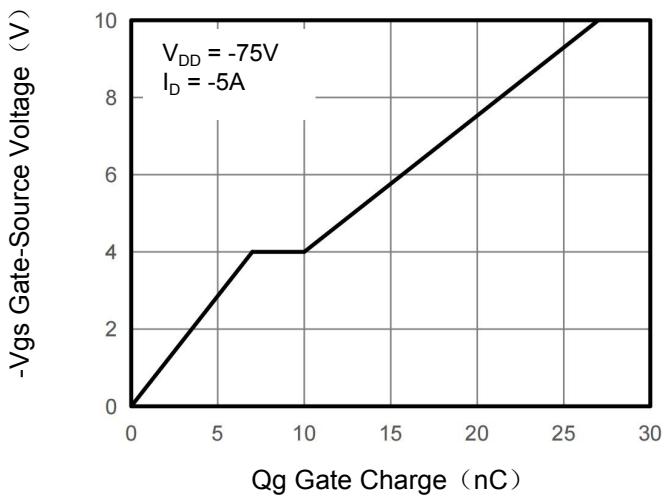


Figure 5. Capacitance

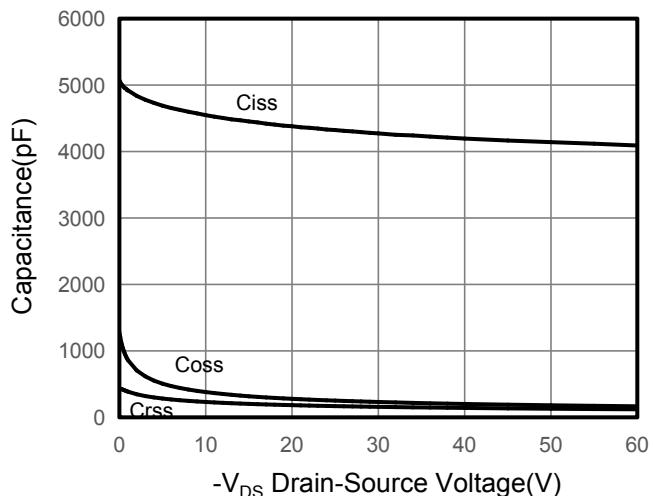
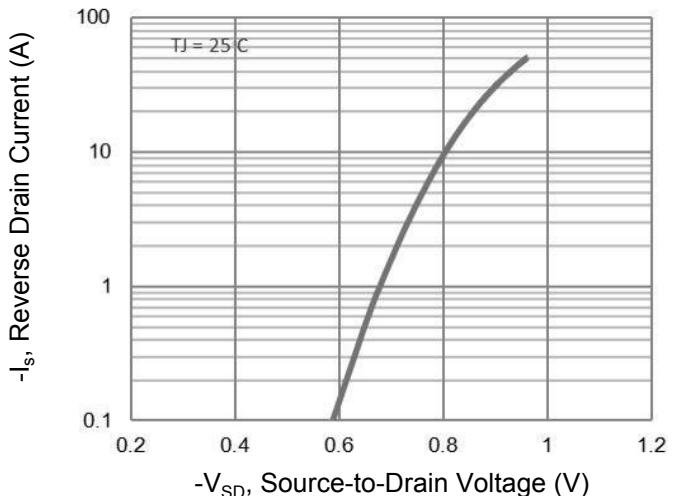


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

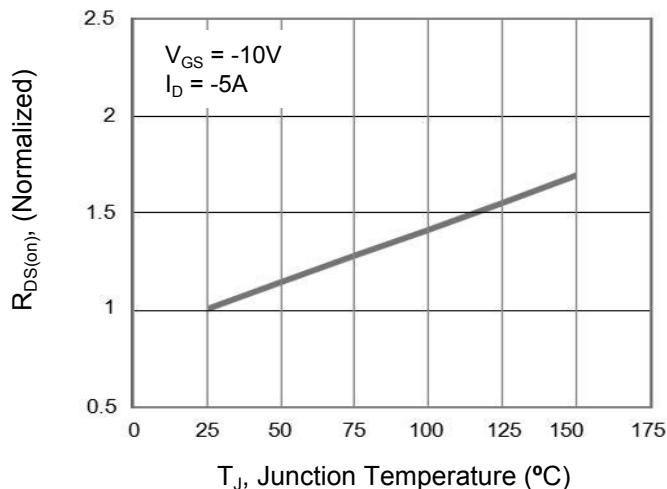


Figure 10. Safe Operation Area

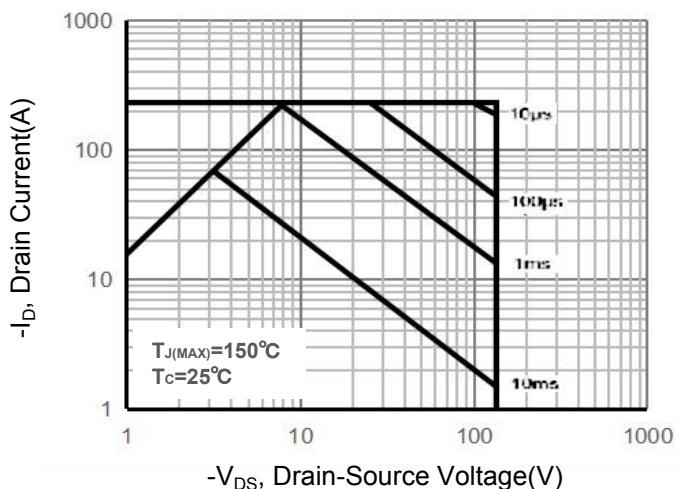
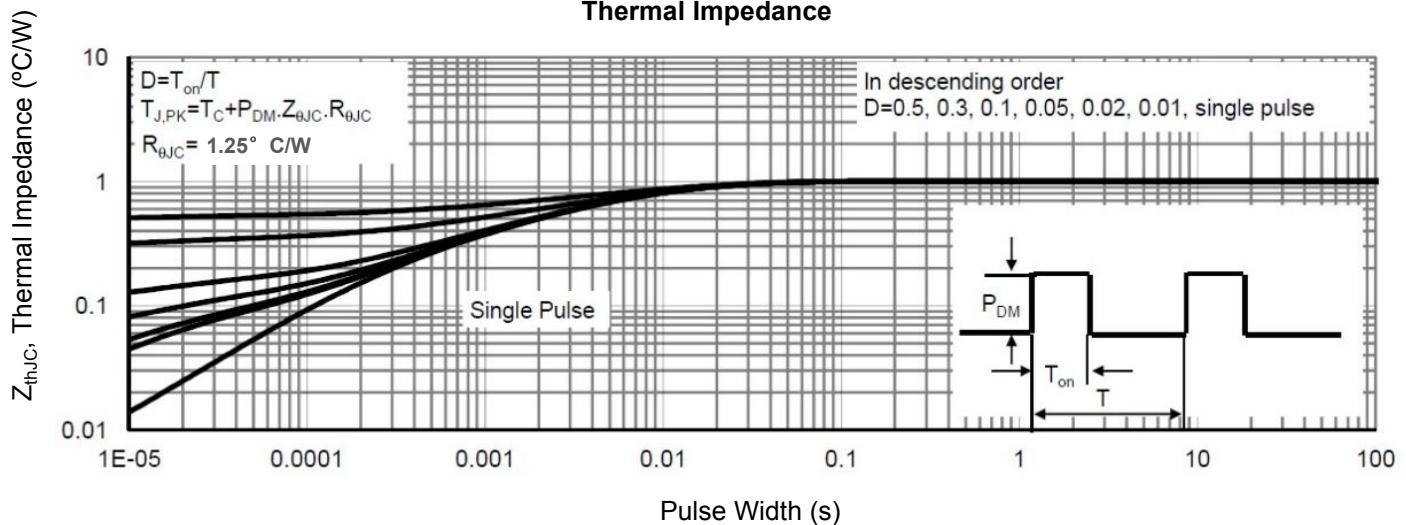
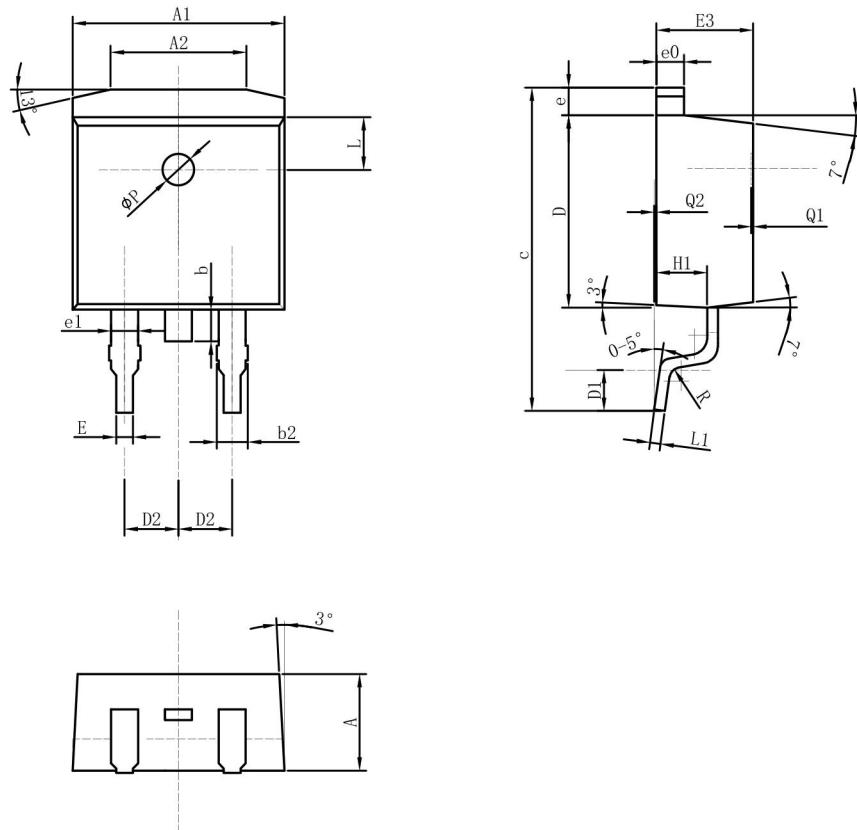


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-263 Package Information



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.52	4.57	4.62
A1	9.95	10.00	10.05
A2	6.30	6.40	6.50
b	1.30	1.50	1.70
b2	1.17	1.27	1.37
c	14.80	15.00	15.20
D	9.05	9.10	9.15
D1	1.90	2.10	2.30
D2	—	2.54	—
E	—	0.80	—
E3	—	4.57	—
e	—	1.30	—
e0	—	1.30	—
e1	1.73	3	—
H1	—	2.40	—
L	—	2.50	—
L1	—	0.50	—
ΦP	—	1.50	—
R	—	0.50	—
Q1	0.10	—	0.15
Q2	0	—	0.02